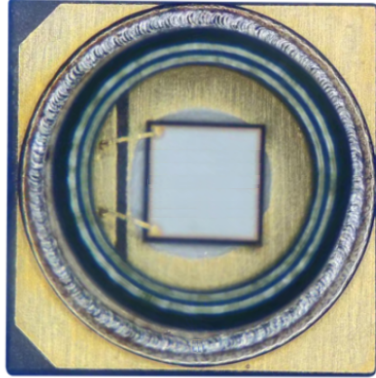




TH-UVxxxT5WSS2000-3535F

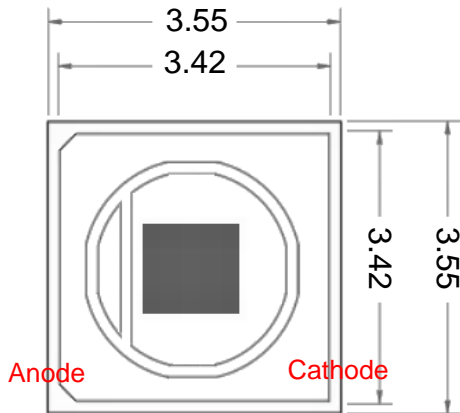


CAUTION

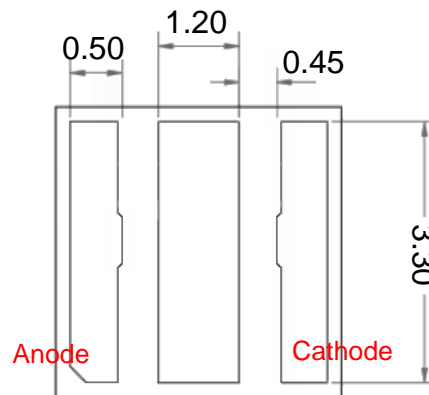
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



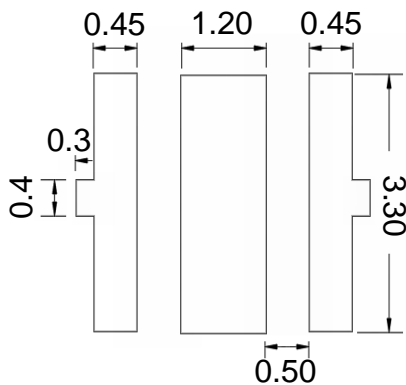
Mechanical Dimensions



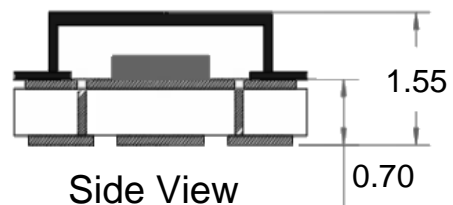
Front Side



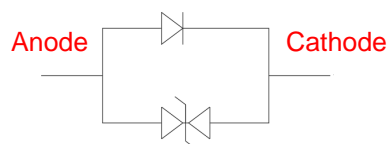
Back Side



Solder Pad of PCB



Side View



Zener Diode

Notes :

- [1] All dimensions are in millimeters.
- [2] Scale : none
- [3] Undefined tolerance is $\pm 0.2\text{mm}$



Electro-Optical characteristics at1500mA

(T_a=25℃, RH=30%)

Items	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Current	I _F			1500		mA
Forward Voltage ^[4]	V _F	I _F =1500mA	3.4	3.8	4.4	V
Radiant Flux ^[2]	Φ _e ^[3]	I _F =1500mA	2000	-	3000	mW
Peak Wavelength ^[1] 365nm:TH-UV365T5WSS2000-3535F 385nm:TH-UV385T5WSS2000-3535F 395nm:TH-UV395T5WSS2000-3535F 405nm:TH-UV405T5WSS2000-3535F 415nm:TH-UV415T5WSS2000-3535F	λ _p	I _F =1500mA	365	-	375	nm
			380	-	390	
			390	-	400	
			400	-	410	
			410	-	420	
Viewing Angle	2θ _{1/2}	I _F =1500mA		120		deg.
Spectrum Half Width	Δλ	I _F =1500mA		12		nm
Thermal Resistance	R _{θj-b}	I _F =1500mA		5.5		°C/W

Absolute Maximum Ratings

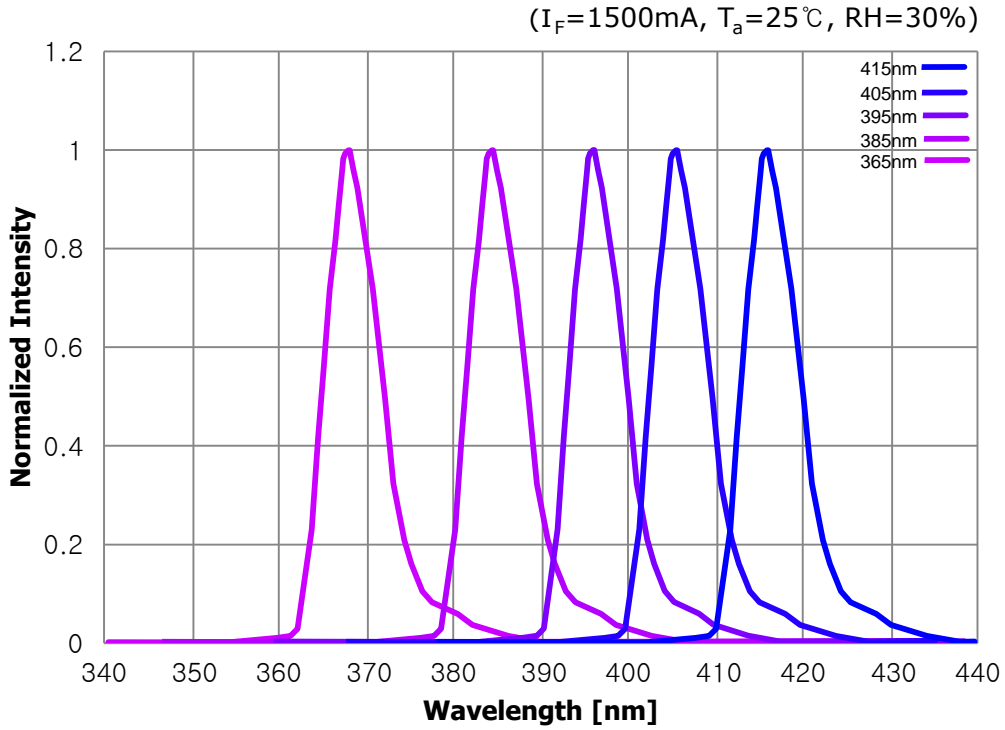
Parameter	Symbol	Absolute maximum Rating	Unit
Forward Current	I _F	1750	mA
Power Dissipation	P _D	6650	mW
Operating Temperature	T _{opr}	-30 ~ +60	°C
Storage Temperature	T _{stg}	-40 ~ +100	°C

Notes :

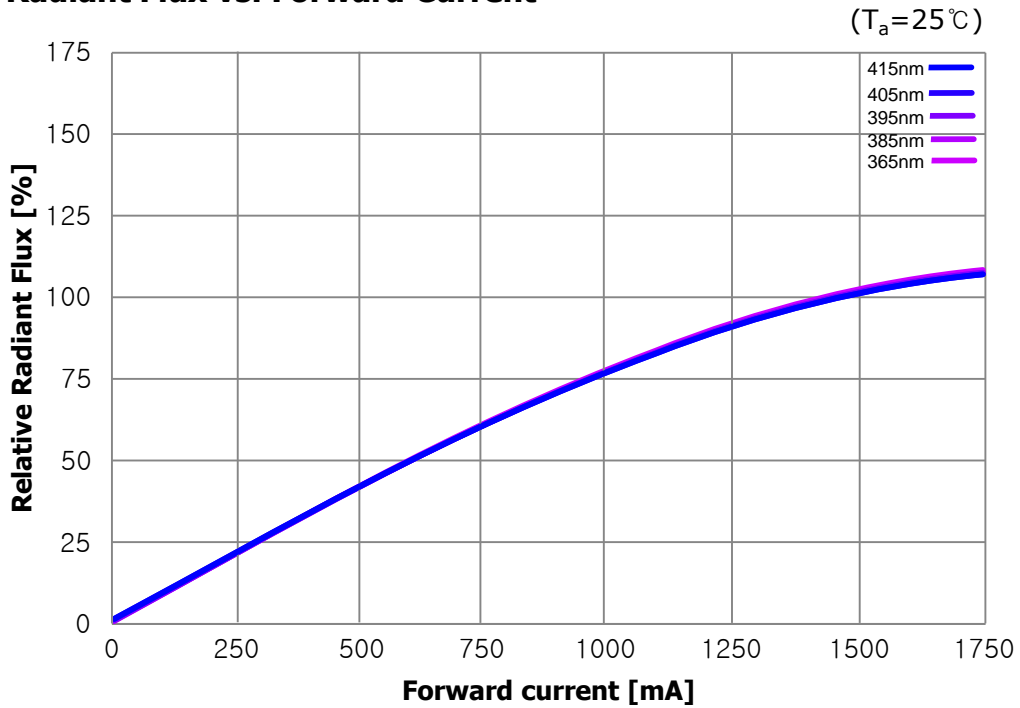
1. Peak Wavelength Measurement tolerance : ±3nm
2. Radiant Flux Measurement tolerance : ± 10%
3. Φ_e is the Total Radiant Flux as measured with an integrated sphere.
4. Forward Voltage Measurement tolerance : ±3%



Spectral Power Distribution

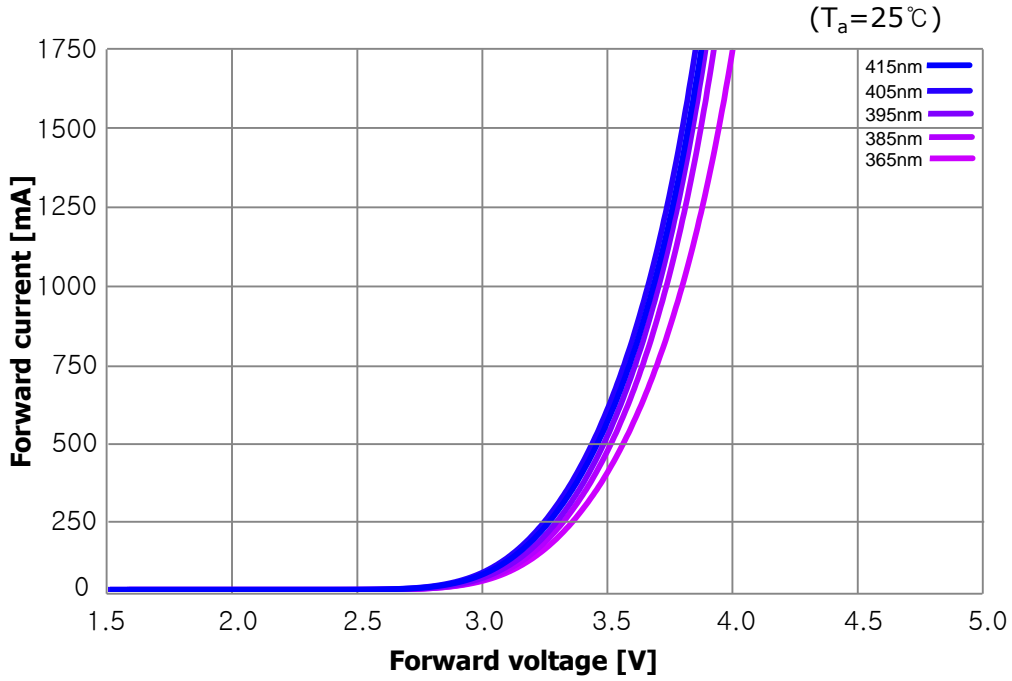


Relative Radiant Flux vs. Forward Current

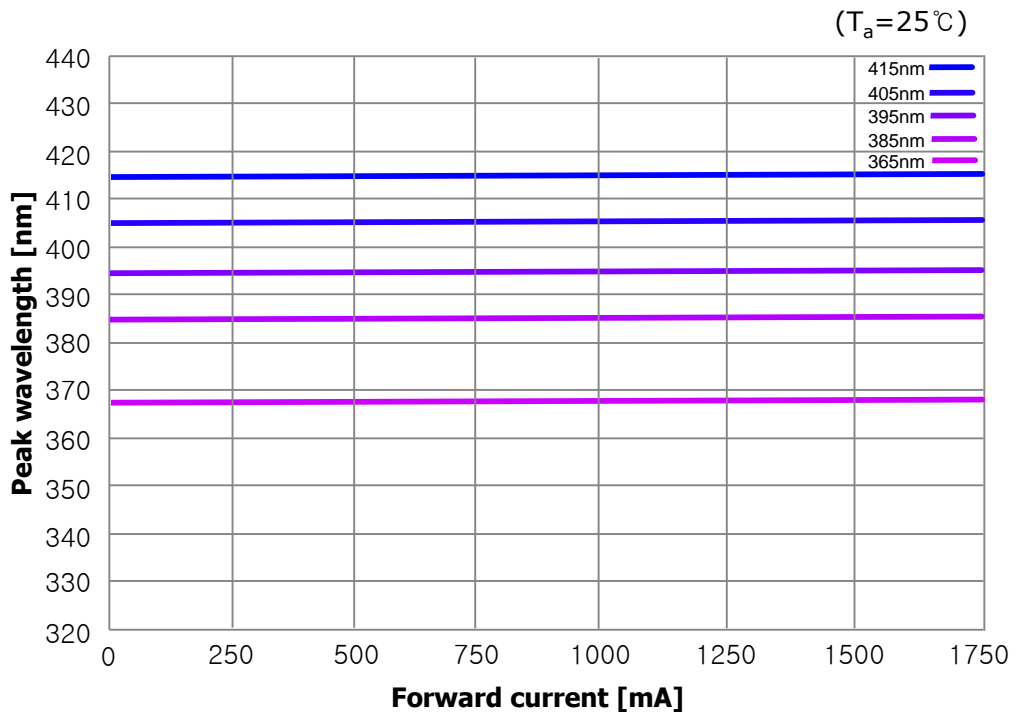




Forward current vs. Forward Voltage

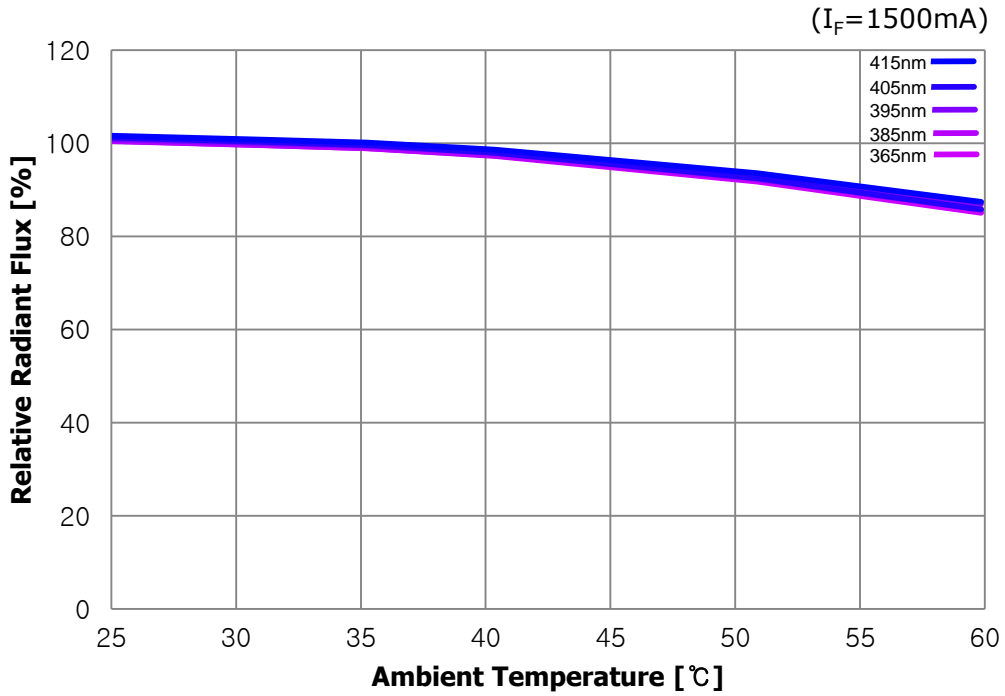


Peak Wavelength vs. Forward current

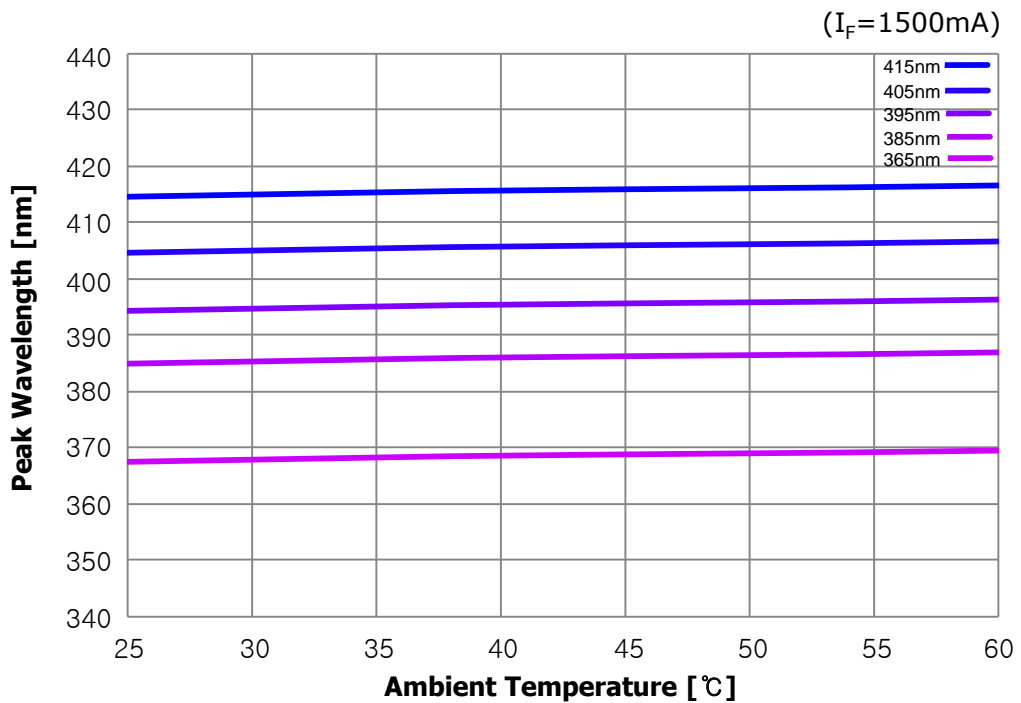




Relative Radiant Flux vs. Ambient Temperature

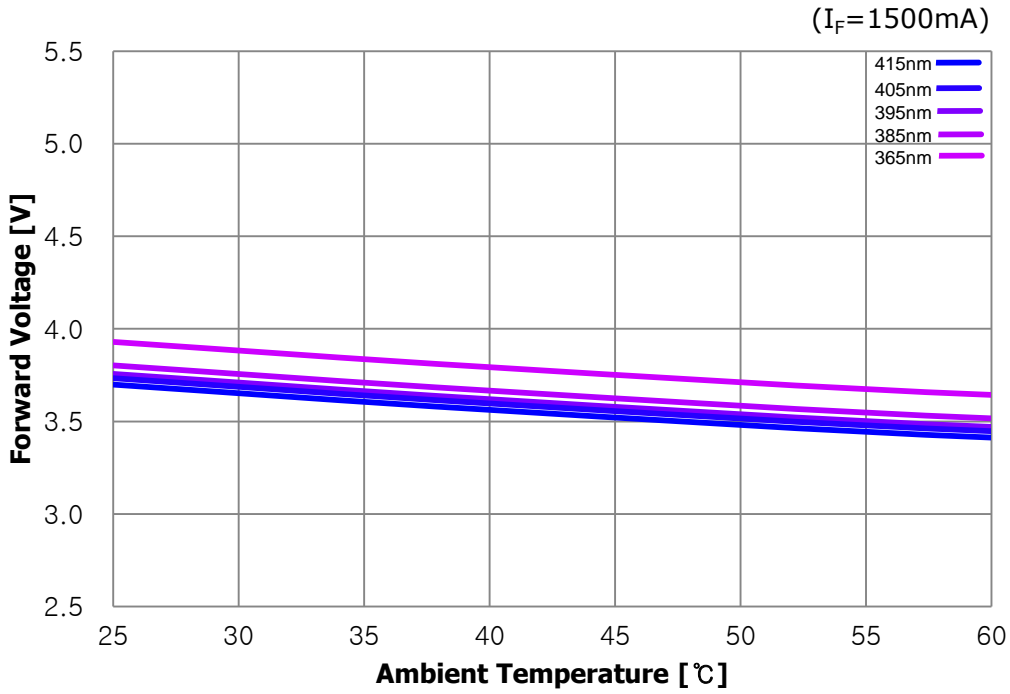


Peak Wavelength vs. Ambient Temperature

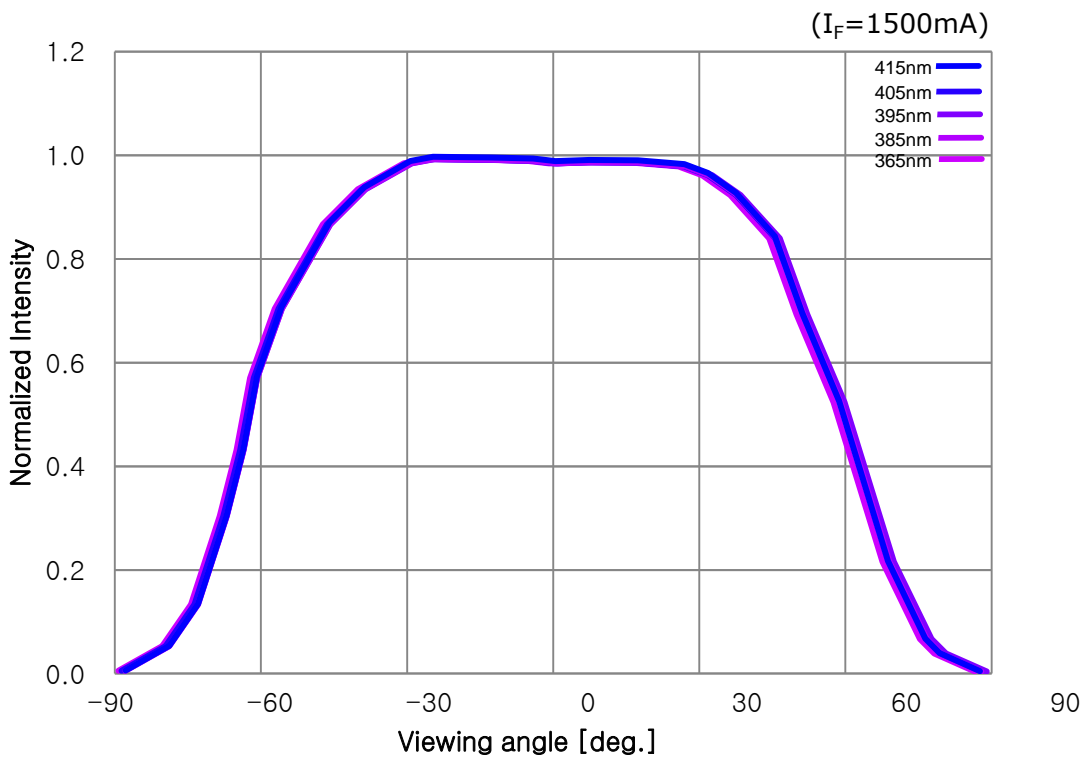


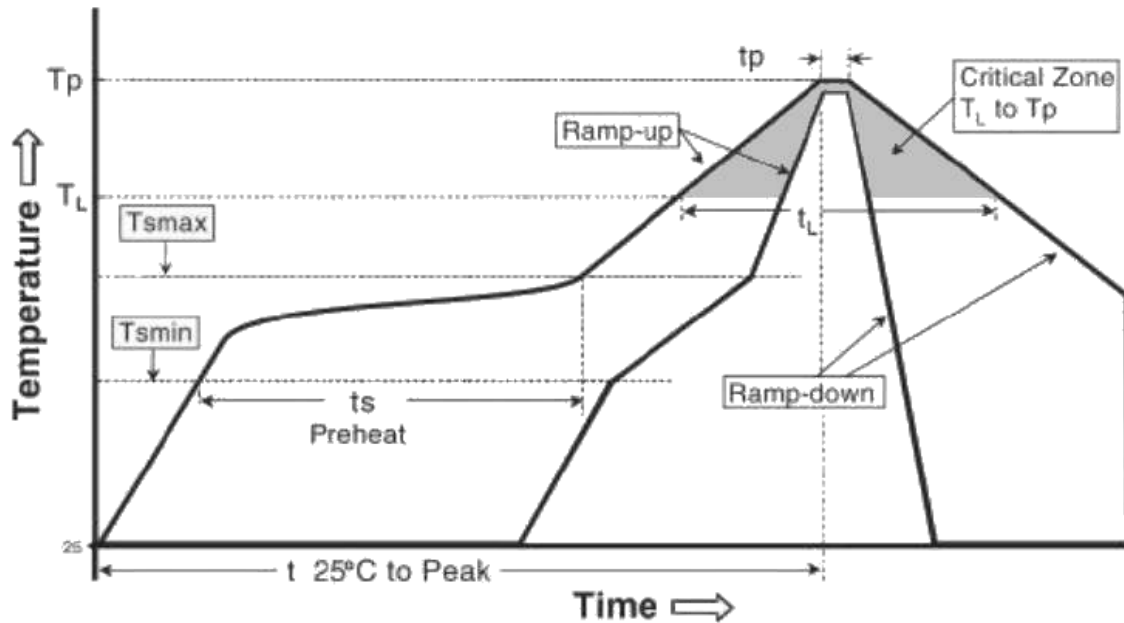


Forward Voltage vs. Ambient Temperature



Radiant Pattern





Profile Feature	Sn-Pb Eutectic Assembly
Average ramp-up rate (Ts_max to Tp)	3 °C/second max.
Preheat	
- Temperature Min (Ts_min)	100 °C
- Temperature Max (Ts_max)	140 °C
- Time (Ts_min to Ts_max) (ts)	60-120 seconds
Time maintained above:	
- Temperature (TL)	180 °C
- Time (tL)	20-50 seconds
Peak Temperature (Tp)	214 °C
Time within 5°C of actual Peak Temperature (tp)	10-30 seconds
Ramp-down Rate	6 °C/second max.
Time 25°C to Peak Temperature	6 minutes max.

*** Caution**

1. Reflow soldering should not be done more than one time.
2. Repairs should not be done after the LEDs have been soldered. When repair is unavoidable, suitable tools must be used.
3. Die slug is to be soldered.
4. When soldering, do not put stress on the LEDs during heating.
5. After soldering, do not warp the circuit board.
6. Recommend to use a convection type reflow machine with 6 ~ 8 zones.